



HDBNC-J-P-GN-ST-EM1



HDBNC-J-P-GN-ST-BH1



HDBNC-J-P-GN-RA-BH1



HDBNC-J-P-GN-ST-TH1

HDBNC SERIES

75 Ω HIGH-DENSITY BNC JACKS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDBNC-BH1 or www.samtec.com?HDBNC-EM1

Shell Material:

Au plated Brass

Contact Material:

Copper Alloy

Insulator Material:

PTFE

Impedance:

75 Ω $\pm 2 \Omega$

Voltage Rating:

500 VAC

Dielectric Withstanding:

1500 Vrms min

Operating Temperature:

-65 °C to +125 °C

RoHS Compliant:

Yes

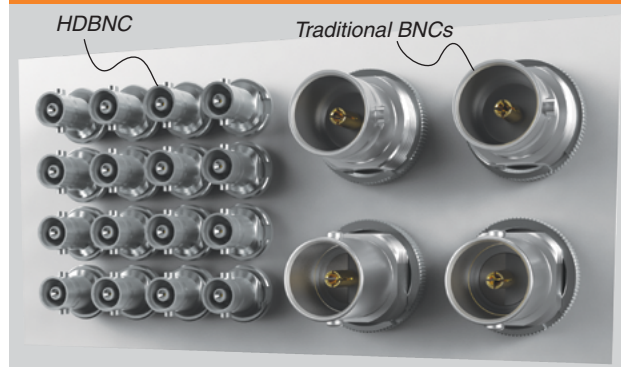
Lead-Free Solderable:

Yes

Mates with:

RFB6T, RFB8T, RFA6T

4X THE PANEL DENSITY



Patented design
and bayonet latch

20% reduction in
weight of traditional
BNCs

Extended
performance
of 12G for
high density
terminations

EXTRACTION TOOL

- Hand tool for quickly installing/uninstalling HDBNC Series.
- Part Number: CAT-EX-HDBNC-01
- Contact Samtec.

HDBNC

GENDER

TYPE

PLATING

ORIENTATION

TERMINATION

—J
= Jack

—P
= PCB
Mount

—GN
= 10 μ "
(0.25 μ m)
Gold
contact,
100 μ "
(2.54 μ m)
Nickel
shell

—ST
= Straight

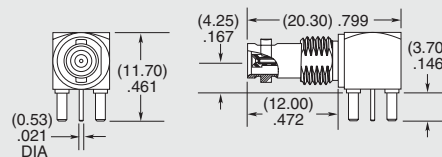
—RA
= Right-angle

—BH1
= Through-hole

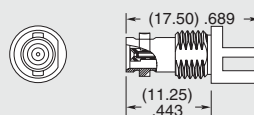
—BH2
= Through-hole
(2.36 mm) .093 Board
(—RA only)

—EM1
= Edge Mount
(—ST only)

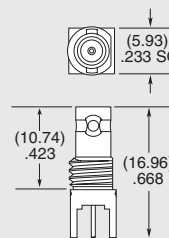
—TH1
= Through-hole
(—ST only)



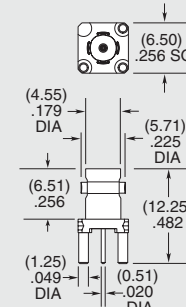
HDBNC-RA



HDBNC-EM1



HDBNC-BH1



HDBNC-TH1

Notes:
Compatible with
Amphenol's HD-BNC™

Designed to meet SMPTE
424M 12G-SDI specifications.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.